# HLN Technologies Limited

Registration No. 200402180C

## Use of IPO and Share Placement Proceeds

The Board of Directors of HLN Technologies Limited (the 'Company') refers to its Prospectus dated 15 November 2005 and wishes to update the use of IPO proceeds as at 30 June 2007.

### Amount of IPO proceeds raised

	<u>S\$"million</u>
Amount raised	4.83
Less: Listing expenses	(1.01)
Net IPO proceeds	3.82

#### Use of IPO proceeds is as follows:-

S/N	Intended Use	Amount	Amount	Balance
		allocated	utilized	amount
		(S\$'million)	(S\$'million)	(S\$'million)
1	To expand in Suzhou	1.30	0.00	1.30
2	To expand in Batam	0.60	0.25	0.35
3	To expand R&D in Singapore	0.20	0.00	0.20
4	To expand polymeric die-cutting in Singapore	0.20	0.20	0.00
5	To implement ERP system for the Group	0.20	0.20	0.00
6	As working capital for the Group	1.32	1.32	0.00
	Total	3.82	1.97	1.85

## Use of Share Placement proceeds

In addition, the Board of Directors of the Company refers to the placement of 9,800,000 ordinary shares in the capital of the Company which was completed on 16 May 2007 and wishes to update the use of the placement proceeds as at 30 June 2007.

#### Amount of placement proceeds raised

	<u>S\$"million</u>
Amount raised	5.39
Less: Listing expenses	(0.19)
Net IPO proceeds	5.20

## Use of placement proceeds is as follows:-

S/N	Intended Use	Amount	Amount	Balance
		allocated	utilized	amount
		(S\$'million)	(S\$'million)	(S\$'million)
1	To expand the Group's metallic business	3.00	3.00	0.00
2	To expand in Malaysia and PRC	1.20	0.00	1.20
3	As working capital for the Group	1.00	0.00	1.00
	Total	5.20	3.00	2.20

The Company will continue to provide regular updates on the use of the balance proceeds.

By order of the Board

Wa Kok Liang Chief Executive Officer 14 August 2007